



Docket No.: 008063 USA MTCG/PINTGR

PATENT/OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re Application of

Deenesh PADHI et al.

Serial No. 10/812,480

Filed: March 30, 2004

For: SELECTIVE METAL ENCAPSULATION SCHEMES

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: Group Art Unit:  
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: Examiner:

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent applications, and possibly other sources.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

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Date: 6/16/04

<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>				ATTY. DOCKET NO. 008063 USA MTCG/PINTGR		SERIAL NO. 10/812,480	
				APPLICANT Deenesh PADHI et al.			
				FILING DATE March 30, 2004		GROUP	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	3,205,485	09/07/65	Noltingk			10/21/60	
	3,229,198	01/11/66	Libby			09/28/62	
	3,767,900	10/23/73	Chao et al.			06/23/71	
	3,920,965	11/18/75	Sohrwardy			03/04/74	
	4,000,458	12/28/76	Miller et al.			08/21/75	
	4,207,520	06/10/80	Flora et al.			04/06/78	
	4,209,744	06/24/80	Gerasimov et al.			03/27/78	
	4,302,721	11/24/81	Urbanek et al.			05/15/79	
	4,368,510	01/11/83	Anderson			10/20/80	
	4,609,870	09/02/86	Lale et al.			09/13/84	
	4,616,308	10/07/86	Morshedi et al.			12/02/85	
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	5,226,118	07/06/93	Baker et al.			01/29/91	
	5,231,585	07/27/93	Kobayashi et al.			06/20/90	
	5,236,868	08/17/93	Nulman			04/20/90	
	5,260,868	11/09/93	Gupta et al.			10/15/91	
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	5,270,222	12/14/93	Moslehi			12/31/90	
	5,283,141	02/01/94	Yoon et al.			03/05/92	
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	5,808,303	09/15/98	Schlagheck et al.			01/29/97	
	5,812,407	09/22/98	Sato et al.			08/12/97	
	5,823,854	10/20/98	Chen			05/28/96	
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	5,910,011	06/08/99	Cruse			05/12/97	
	5,910,846	06/08/99	Sandhu			08/19/97	
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	5,912,678	06/15/99	Saxena et al.			04/14/97	
	5,916,016	06/29/99	Bothra			10/23/97	
	5,923,553	07/13/99	Yi			10/05/96	
	5,926,690	07/20/99	Toprac et al.			05/28/97	
	5,930,138	07/27/99	Lin et al.			09/10/97	
	5,940,300	08/17/99	Ozaki			05/08/97	
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	5,960,185	09/28/99	Nguyen			06/24/96	
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96	
	5,961,369	10/05/99	Bartels et al.			06/04/98	
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	6,002,989	12/14/99	Shiba et al.			04/01/97	
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	6,054,379	04/25/00	Yau et al.			02/11/98	
	6,064,759	05/16/00	Buckley et al.			11/06/97	
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	6,108,092	08/22/00	Sandhu			06/08/99	
	6,111,634	08/29/00	Pecen et al.			05/28/97	
	6,112,130	08/29/00	Fukuda et al.			10/01/97	
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	6,127,263	10/03/00	Parikh			07/10/98	
	6,128,016	10/03/00	Coelho et al.			12/20/96	
	6,136,163	10/24/00	Cheung et al.			03/05/99	
	6,141,660	10/31/00	Bach et al.			07/16/98	
	6,148,099	11/14/00	Lee et al.			07/03/97	
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	6,159,075	12/12/00	Zhang			10/13/99	
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				APPLICANT Deenesh PADHI et al.			
				FILING DATE March 30, 2004		GROUP	
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow			
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes			
	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions			
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
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	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
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	10/377,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data			
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	10/632,107	08/01/03	Schwarm et al.	Method, System, and Medium for Handling Misrepresentative Metrology Data Within an Advanced Process Control System			
	10/665,165	09/18/03	Paik	Feedback Control of a Chemical Mechanical Polishing Process for Multi-Layered Films			
	10/712,273	11/14/03	Kokotov	Method, System and Medium for Controlling Manufacture Process Having Multivariate Input Parameters			
	10/759,108	01/20/04	Schwarm	Automated Design and Execution of Experiments with Integrated Model Creation for Semiconductor Manufacturing Tools			
	10/765,921	01/29/04	Schwarm	System, Method, and Medium for Monitoring Performance of an Advanced Process Control System			
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				<b>APPLICANT</b> Deenesh PADHI et al.					
				<b>FILING DATE</b> March 30, 2004				<b>GROUP</b>	
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<b>EXAMINER'S INITIALS</b>	<b>PATENT APP. NO.</b>	<b>FILING DATE</b>	<b>NAME</b>	<b>TITLE</b>	<b>CLASS</b>	<b>SUB- CLASS</b>			
	10/809,906	03/26/04	Surana et al.	A Technique for Process-Qualifying a Semiconductor Manufacturing Tool Using Metrology Data					
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<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	EP 0 869 652 A2	10/07/98	Europe			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 877 308 A2	11/11/98	Europe			X	
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	WO 99/09371	02/25/99	WO			X	
	11-67853	03/09/99	Japan			X	
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	11-126816	05/11/99	Japan			X	
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	WO 99/25520	05/27/99	WO			X	
	EP 0 932 194 A1	07/28/99	Europe			X	
	WO 99/59200	11/18/99	WO			X	
	WO 00/00874	01/06/00	WO			X	
	WO 00/05759	02/03/00	WO			X	
	WO 00/35063	06/15/00	WO			X	
	2000-183001	06/30/00	Japan			X	
	WO 00/54325	09/14/00	WO			X	
	GB 2 347 885 A	09/20/00	United Kingdom			X	
	WO 00/79355 A1	12/28/00	WO			X	
	EP 1 066 925 A2	01/10/01	Europe			X	
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	WO 01/11679 A1	02/15/01	WO			X	
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	WO 01/18623 A1	03/15/01	WO			X	
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
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	2,050,247	08/29/91	Canada			X	
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	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
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						Yes	No
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、	EP 1 182 526 A2	02/27/02	Europe			X	
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	WO 02/31613 A3	04/18/02	WO			X	
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	<p>APPLICANT Deenesh PADHI et al.</p>	
	<p>FILING DATE March 30, 2004</p>	<p>GROUP</p>
<p align="center"><b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b></p>		
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<p align="center"><b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b></p>	<p>ATTY. DOCKET NO. 008063 USA MTCG/PINTGR</p>	<p>SERIAL NO. 10/812,480</p>
	<p>APPLICANT Deenesh PADHI et al.</p>	
	<p>FILING DATE March 30, 2004</p>	<p>GROUP</p>
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